

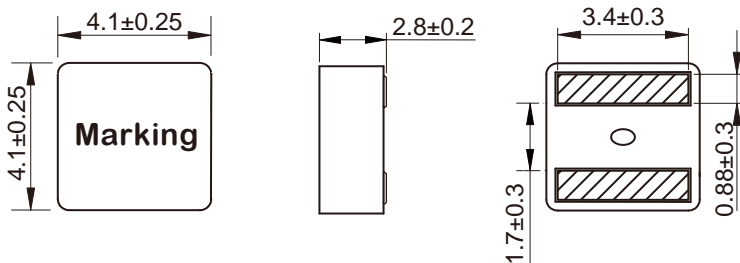
MDTA Series

Flat Wire Molded Inductor

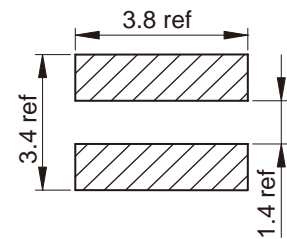
Size 4030



Dimensions: [mm]



Land Pattern: [mm]



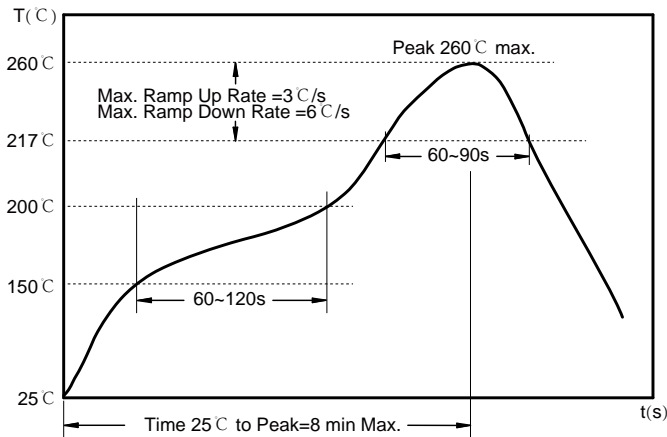
Electrical Properties:

	(μ H)		(A)			(m)
MDTA4030-R47M	0.47	±20%	17.0	10.0	14.0	7.26
MDTA4030-R90M	0.90	±20%	10.0	8.2	11.2	10.1
MDTA4030-1R0M	1.00	±20%	9.80	8.0	11.0	10.1
MDTA4030-1R2M	1.20	±20%	9.20	7.8	9.80	11.5
MDTA4030-1R5M	1.50	±20%	8.00	7.0	9.00	13.2
MDTA4030-2R2M	2.20	±20%	7.00	6.0	7.80	22.6
MDTA4030-3R3M	3.30	±20%	6.20	5.0	6.60	28.6

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current that causes the specified temperature rise from 25°C ambient.

Soldering Reflow:



Preheat condition: 150 ~200°C / 60~120 sec.

Allowed time above 217°C : 60~90 sec.

Max temperature: 260°C .

Max time at max temperature: 10 sec.

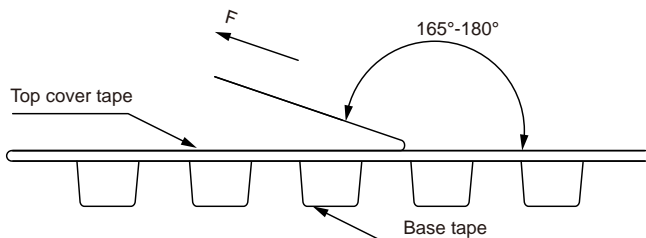
Allowed Reflow time: 2x max.

Packaging Information:

Tape Dimension :

Series	A0 (mm)	B0 (mm)							
MDTA4030	4.5± 0.1	4.5± 0.1	1.5± 0.1	4.0± 0.1	8.0± 0.1	12.0± 0.3	3.3± 0.1	1.75± 0.1	

Peel force of top cover tape:

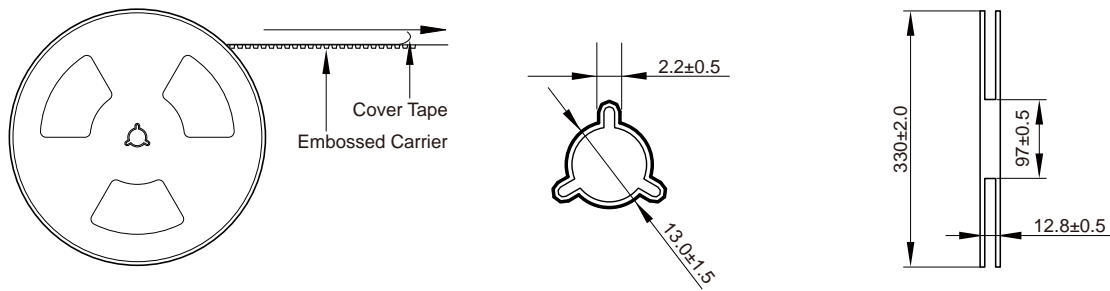


The peel force of top cover tape shall be between 0.1 to 1.3 N

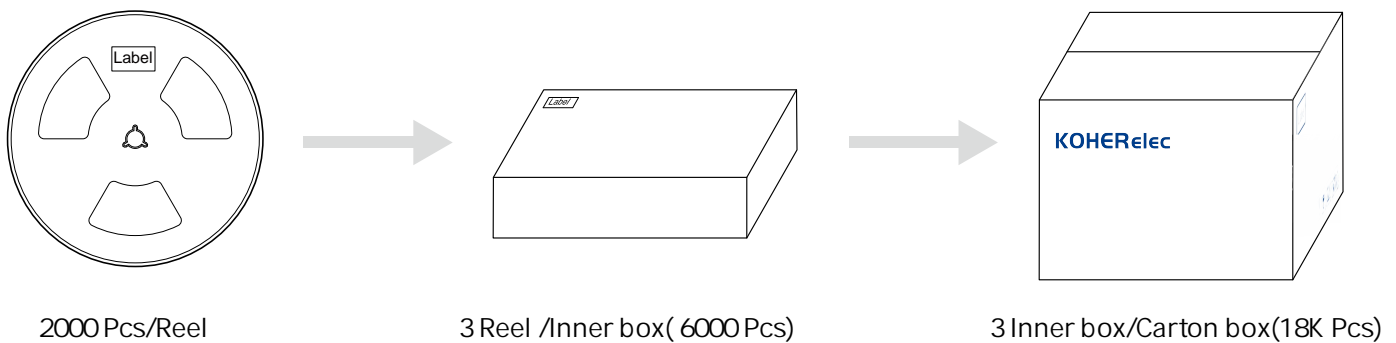
Product Marking:

Marking	Printing Inductance)
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Reel Dimension: [mm]



Packaging Quantity:



Cautions and Warnings:

Storage Conditions:

- The storage period is within 12 months after the completion of production. Be sure to follow the storage conditions (temperature: -5 to 35°C, humidity: 75% RH Max). If the storage period elapses, the soldering of the terminal electrodes may deteriorate. The warranty period is one year.
- Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and etc.
- Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- Please always handle products carefully to prevent any damage caused by dropping down or inappropriate removing.

Operation Instructions:

- Self heating (temperature increase) occurs when the power is turned ON, so the tolerance should be sufficient for the set thermal design.
- Before soldering, be sure to preheat components. The preheating temperature should be set so that the temperature difference between the solder temperature and chip temperature does not exceed 150°C.
- Soldering corrections after mounting should be within the range of the conditions determined in the specifications. If overheated, a short circuit, performance deterioration, or lifespan shortening may occur.
- Generally, Koher might not be familiar with either customer's specific application or actual requests as customer does. As a result customer shall be responsible for checking and confirming whether Koher product with the performance described in the product specification is suitable for using in customer's particular application or not.